

LISTING OF CLAIMS

Claims 1-14. (Cancelled)

Claim 15. (Original) A method of a photolithography processing system comprising:
illuminating a surface of a wafer with first and second illuminating tools;
taking pictures of the surface of the wafer with a camera while the surface of the wafer is being illuminated;
receiving a signal from the camera in a controller;
detecting a presence of particles on the surface of the wafer with the controller; and
transporting the wafer to the process-performing or cleaning position according to whether particles are detected on the surface of the wafer.

Claim 16. (Original) The method of a photolithography processing system as claimed in claim 15, wherein the illuminating of the surface of the wafer comprises:
positioning a plurality of first illumination tools at varying lateral heights relative to the table to illuminate the surface of the wafer at predetermined angles of incidence; and
positioning the second illumination tool to illuminate the surface of the wafer vertically from above the wafer on the table.

Claim 17. (Original) The method of a photolithography processing system as claimed in claim 15, wherein the taking of pictures of the surface of the wafer comprises:

- obtaining a first image while the first illumination tools are maintained in an 'on' position and the second illumination tool is maintained in an 'off' position;
- obtaining a second image while the first illumination tools are maintained in an 'off' position and the second illumination tool is maintained in an 'on' position; and
- forming a multi-dimensional image by combining the first and second images.